


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/21/12790	
1.3 Title of PCN	TSMC (USA) Wafer Fab additional source for STM32F107 256K listed products	
1.4 Product Category	STM32F107 256K	
1.5 Issue date	2021-06-10	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	TSMC (Taiwan) Wafer Fab

**4. Description of change**

	<b>Old</b>	<b>New</b>
4.1 Description	Wafer diffusion plants : - TSMC Taiwan Wafer Fab 3	Wafer diffusion plants : - TSMC Taiwan Wafer Fab 3 - TSMC USA Wafer Fab 11  There is no change in the product functionality.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

**5. Reason / motivation for change**

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

6.1 Description	Traceability of the change is ensured by ST internal tools. Change is visible through diffusion traceability plant, in the marking: - "93" for TSMC Taiwan Wafer Fab 3 - "9U" for TSMC USA Wafer Fab 11 Please refer to PCN 12790 – Additional information attached document.
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**7. Timing / schedule**

7.1 Date of qualification results	2021-05-28
7.2 Intended start of delivery	2021-07-30
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	12790 MDG-MCD RER2104 V1.0 - PCN12790 - Wafer Fab additional source for STM32F107 256K Transfer Fab11 - reliability Evaluation Report.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2021-06-10

**9. Attachments (additional documentations)**

12790 Public product.pdf  
 12790 MDG-MCD RER2104 V1.0 - PCN12790 - Wafer Fab additional source for STM32F107 256K Transfer Fab11 - reliability Evaluation Report.pdf  
 12790 PCN12790\_Additional information.pdf

**10. Affected parts**

10. 1 Current			10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	STM32F105R8T6		
	STM32F105RBT6		
	STM32F105RCT6		
	STM32F105VCT6		
	STM32F105VCT7		
	STM32F107RCT6		
	STM32F107VCH6		
	STM32F107VCT6		

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